



Prof. Rao Tummala is a Distinguished and Endowed Chair Professor at Georgia Tech USA. He is well known as an industrial technologist, technology pioneer, and educator. Prior to joining Georgia Tech, he was an IBM Fellow, pioneering such major technologies as the industry's first plasma display and the first and next three generations of 100 chip multi-chip packaging. He is the father of LTCC and System-on-Package technologies. As an educator, Prof. Tummala was instrumental in setting up the largest Academic Center in Electronic Systems at Georgia Tech involving more than 100 PhD and MS students, 25 faculty from ECE, ME, MSE and CHE, and 70 companies from the U.S., Europe and Asia, all working together with an integrated approach to research, education and industry collaborations. He has published 700 technical papers and invented 98 patents, wrote the first textbook in packaging, Microelectronics Packaging Handbook, wrote the 1st undergrad textbook Fundamentals of Microsystem Packaging and the 1st book introducing the System-On-Package Concept.